Unit: mm

TOSHIBA Field Effect Transistor Silicon P/N Channel MOS Type

SSM6L16FE

High Speed Switching Applications Analog Switch Applications

• Small package

Low on-resistance

Q1: $R_{on} = 4 \Omega \text{ (max) } (@V_{GS} = 2.5 \text{ V})$

Q2: $R_{on} = 12 \Omega \text{ (max) } (@V_{GS} = -2.5 \text{ V})$

Q1 Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V_{DS}	20	V
Gate-Source voltage		V_{GSS}	±10	٧
Drain current	DC	ΙD	100	mA
	Pulse	I _{DP}	200	Ш

Q2 Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-Source voltage		V_{DS}	-20	V
Gate-Source voltage		V_{GSS}	±10	V
Drain current	DC	ΙD	-100	mA
	Pulse	I_{DP}	-200	IIIA

1: Source1 2: Gate1 3: Drain2 4: Source2 5: Gate2 ES6 6: Drain1 JEDEC JEITA 1.6±0.05 900+91 900+9

2-2N1D

TOSHIBA

Absolute Maximum Ratings (Q1, Q2 Common) (Ta = 25°C)

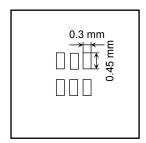
Characteristics	Symbol	Rating	Unit
Drain power dissipation (Ta = 25°C)	P _D (Note 1)	150	mW
Channel temperature	T _{ch}	150	°C
Storage temperature range	T _{stg}	-55~150	°C

Note:

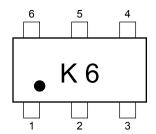
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

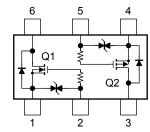
Note 1: Total rating, mounted on FR4 board (25.4 mm \times 25.4 mm \times 1.6 t, Cu Pad: 0.135 mm 2 \times 6)



Marking



Equivalent Circuit (top view)



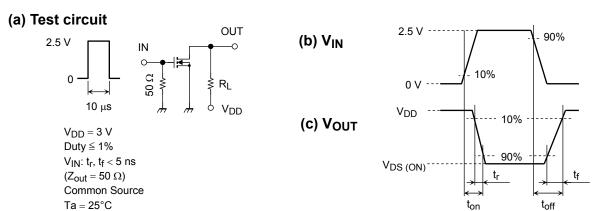
Handling Precaution

When handling individual devices (which are not yet mounted on a circuit board), ensure that the environment is protected against static electricity. Operators should wear anti-static clothing, and containers and other objects that come into direct contact with devices should be made of anti-static materials.

Q1 Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	MIN.	TYP.	MAX.	UNIT
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$	_	_	±1	μА
Drain-Source breakdown voltage		V (BR) DSS	$I_D = 0.1 \text{ mA}, V_{GS} = 0$	20	_	_	V
Drain cut-off current		I _{DSS}	V _{DS} = 20 V, V _{GS} = 0	_	_	1	μА
Gate threshold voltage		V_{th}	$V_{DS} = 3 \text{ V}, I_D = 0.1 \text{ mA}$	0.6	_	1.1	V
Forward transfer admittance		Y _{fs}	$V_{DS} = 3 \text{ V}, I_D = 10 \text{ mA}$	40	_	_	mS
Drain-Source on-resistance		R _{DS} (ON)	$I_D = 10$ mA, $V_{GS} = 4$ V	_	1.5	3.0	Ω
			I _D = 10 mA, V _{GS} = 2.5 V	_	2.2	4.0	
			I _D = 1 mA, V _{GS} = 1.5 V	_	5.2	15	
Input capacitance		C _{iss}	V _{DS} = 3 V, V _{GS} = 0, f = 1 MHz	_	9.3	_	pF
Reverse transfer capacitance		C _{rss}		_	4.5	_	pF
Output capacitance		C _{oss}		_	9.8	_	pF
Switching time	Turn-on time	t _{on}	$V_{DD} = 3 \text{ V}, I_D = 10 \text{ mA}, \\ V_{GS} = 0~2.5 \text{ V}$	_	70	_	nS
	Turn-off time	t _{off}		_	125	_	113

Switching Time Test Circuit



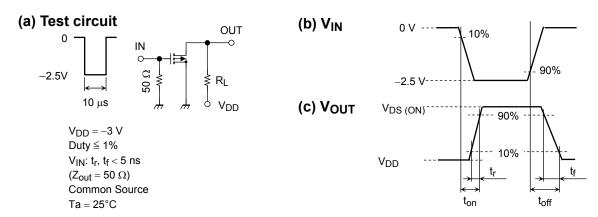
Precaution

 V_{th} can be expressed as the voltage between the gate and source when the low operating current value is $I_D = 100~\mu A$ for this product. For normal switching operation, V_{GS} (on) requires a higher voltage than V_{th} and V_{GS} (off) requires a lower voltage than V_{th} . (The relationship can be established as follows: V_{GS} (off) $< V_{th} < V_{GS}$ (on).) Be sure to take this into consideration when using the device.

Q2 Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	MIN.	TYP.	MAX.	UNIT
Gate leakage current		I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$	_	_	±1	μА
Drain-Source breakdown voltage		V (BR) DSS	$I_D = -0.1 \text{ mA}, V_{GS} = 0$	-20	_	_	V
Drain cut-off current		I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0$	_	_	-1	μА
Gate threshold voltage		V_{th}	$V_{DS} = -3 \text{ V}, I_D = -0.1 \text{ mA}$	-0.6	_	-1.1	V
Forward transfer admittance		Y _{fs}	$V_{DS} = -3 \text{ V}, I_D = -10 \text{ mA}$	25	_	_	mS
			$I_D = -10 \text{ mA}, V_{GS} = -4 \text{ V}$	_	6	8	Ω
Drain-Source on-resist	Drain-Source on-resistance		$I_D = -10 \text{ mA}, V_{GS} = -2.5 \text{ V}$	_	8	12	
			$I_D = -1 \text{ mA}, V_{GS} = -1.5 \text{ V}$	_	18	45	
Input capacitance		C _{iss}	V _{DS} = -3 V, V _{GS} = 0, f = 1 MHz	_	11	_	pF
Reverse transfer capacitance		C _{rss}		_	3.7	_	pF
Output capacitance		C _{oss}		_	10	_	pF
Switching time	Turn-on time	t _{on}	$V_{DD} = -3 \text{ V}, I_{D} = -10 \text{ mA},$	_	130	_	20
	Turn-off time	t _{off}	$V_{GS} = 0 \sim -2.5 \text{ V}$	_	190	_	ns

Switching Time Test Circuit

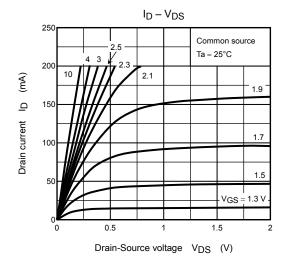


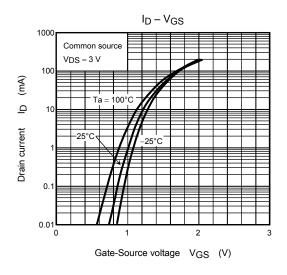
Precaution

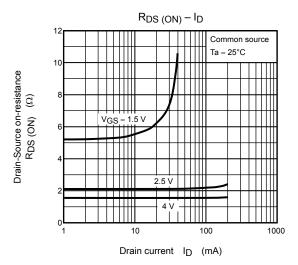
 $V_{th} \ can \ be \ expressed \ as \ the \ voltage \ between \ gate \ and \ source \ when \ the \ low \ operating \ current \ value \ is \ I_D = 100 \ \mu A$ for this product. For normal switching operation, V_{GS} (on) requires a higher voltage than V_{th} and V_{GS} (off) requires a lower voltage than V_{th} . (The relationship can be established as follows: V_{GS} (off) $< V_{th} < V_{GS}$ (on).)

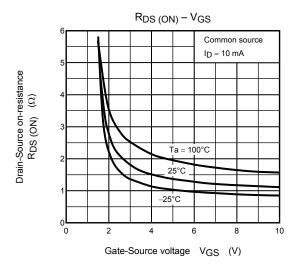
Please take this into consideration when using the device.

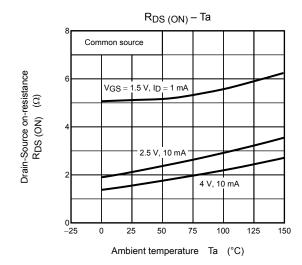
Q1 (N-ch MOSFET)

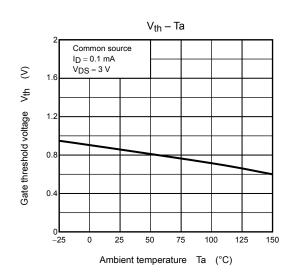




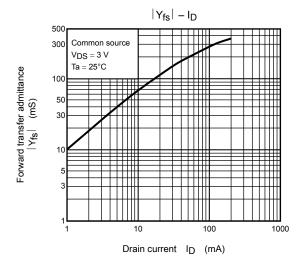


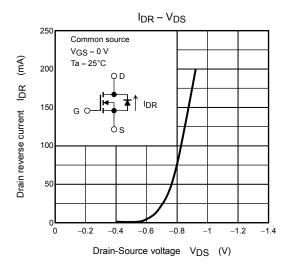


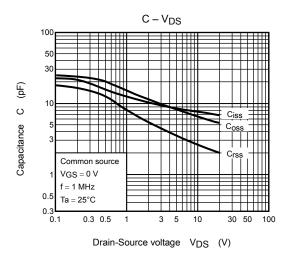


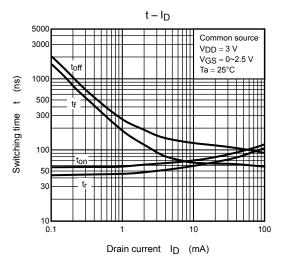


Q1 (N-ch MOSFET)

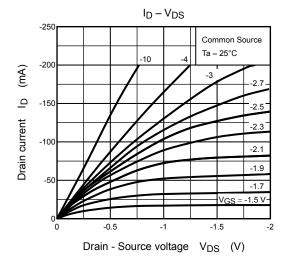


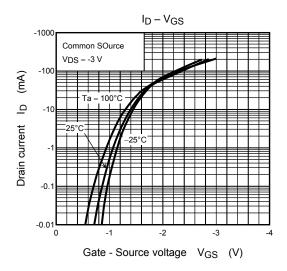


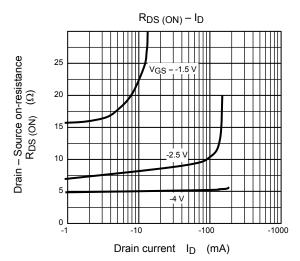


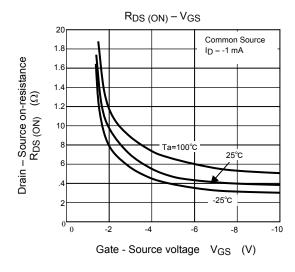


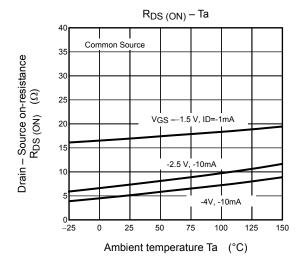
Q2 (P-ch MOSFET)

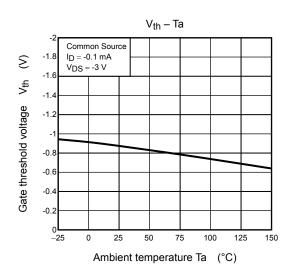




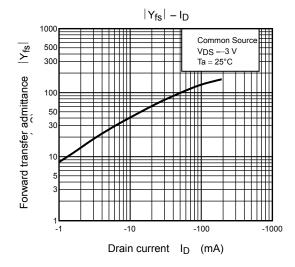


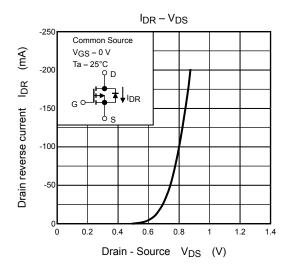


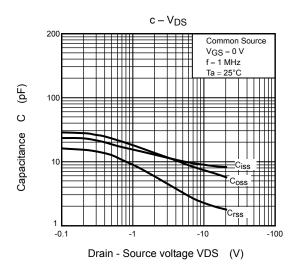


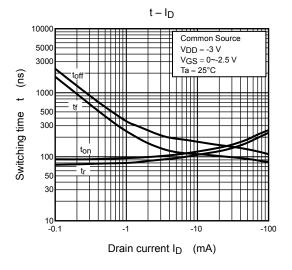


Q2 (P-ch MOSFET)

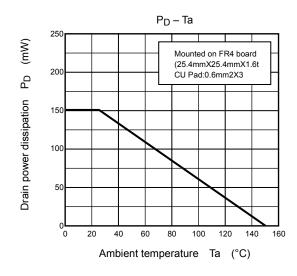








Common Characteristics



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20070701-EN GENERAL

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